

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

1. (Currently Amended) A mask for deposition of material on a flat display, the mask comprising:

a first substrate having a plurality of first via holes formed therein; and

a second substrate positioned on the first substrate, the second substrate having a plurality of second via holes formed therein, wherein the first via holes and the second via holes are arranged so as to overlap with each other, and wherein each second via hole has a width greater than a width of a corresponding first via hole, wherein the plurality of first via holes define deposition areas on the flat display on which source material is to be deposited.

2. (Currently Amended) The ~~shadow~~ mask as claimed in claim 1, wherein a thickness of the second substrate is greater than a thickness of the first substrate.

3. (Currently Amended) The ~~shadow~~ mask as claimed in claim 2, wherein the first substrate is between approximately 1 and 100 μ m thick, and the second substrate is between approximately 5 and 1000 μ m thick.

4. (Currently Amended) The ~~shadow~~ mask as claimed in claim 1, wherein each first via hole and corresponding second via hole have a difference in width of between approximately 1 and 1000 μ m.

5. (Currently Amended) The ~~shadow~~ mask as claimed in claim 1, wherein the plurality of first via holes are arranged in columns along the first substrate, and the plurality of second via holes are arranged on the second substrate such that each column of first via holes is aligned with one corresponding second via hole.

6. (Currently Amended) The ~~shadow~~ mask as claimed in claim 5, wherein the first and second via holes have a form selected from a circle, a polygon, and stripe.

7. (Currently Amended) The ~~shadow~~ mask as claimed in claim 1, further comprising a bridge formed on the first substrate between adjacent first via holes.

8. (Currently Amended) The ~~shadow~~ mask as claimed in claim 7, wherein a thickness of the bridge is substantially the same as a thickness of the second substrate.

9. (Currently Amended) The ~~shadow~~ mask as claimed in claim 7, wherein the bridge is configured to cross the corresponding second via hole.

10. (Currently Amended) A ~~shadow~~ mask for deposition of material on a flat display, the mask comprising:

a first substrate having a plurality of first via holes formed therein;

a second substrate positioned on the first substrate, the second substrate having a

plurality of second via holes formed therein; and

a third substrate provided on the second substrate, the third substrate having a plurality of third via holes formed therein, wherein the first, second, and third via holes are arranged so as to overlap with one another, wherein a width of each second via hole is greater than a width of a corresponding first via hole, and wherein a width of each third via hole is greater than a width of a corresponding second via hole, wherein the plurality of first via holes define deposition areas on the flat display on which source material is deposited.

11. (Currently Amended) The ~~shadow~~ mask as claimed in claim 10, wherein a thickness the second substrate is greater than a thickness of the first substrate or a thickness of third substrate.

12. (Currently Amended) The ~~shadow~~ mask as claimed in claim 11, wherein the first substrate or the third substrate is approximately 1 - 100 μ m thick, and the second substrate is approximately 5 - 1000 μ m thick.

13. (Currently Amended) The ~~shadow~~ mask as claimed in claim 10, wherein each first via hole and corresponding second via hole, or each second via hole and corresponding third via hole, have a difference in width of approximately 1 - 1000 μ m.

14. (Currently Amended) The ~~shadow~~ mask as claimed in claim 10, wherein the plurality of the first via holes are arranged in columns along the first substrate, and the plurality

of second via holes or the plurality of third via holes are arranged on the second and third substrate, respectively, such that each column of first via holes is aligned with one corresponding second via hole or one corresponding third via hole.

15. (Currently Amended) The ~~shadow~~ mask as claimed in claim 14, wherein the first, second, and third via holes have forms selected from a circle, a polygon, and stripe.

16. (Currently Amended) The ~~shadow~~ mask as claimed in claim 10, further comprising a bridge formed on the first substrate between adjacent first via holes.

17. (Currently Amended) The ~~shadow~~ mask as claimed in claim 16, wherein a thickness of the bridge is substantially the same as a thickness of the second substrate.

18. (Currently Amended) The ~~shadow~~ mask as claimed in claim 16, wherein the bridge is configured to cross a corresponding second via hole.

19. (Currently Amended) The ~~shadow~~ mask as claimed in claim 11, wherein the thickness of the second substrate is greater than the thickness of the second substrate, and also greater than the thickness of the third substrate.

20. (Currently Amended) The ~~shadow~~ mask as claimed in claim 12, wherein the first and third substrates are each approximately 1-100 μm thick.

21. (Currently Amended) The ~~shadow~~ mask as claimed in claim 13, wherein each first via hole and corresponding second via hole have a difference in width of approximately 1-1000 μm , and each second via hole and corresponding third via hole have a difference in width of approximately 1 - 1000 μm .

22. (Currently Amended) The ~~shadow~~ mask as claimed in claim 14, wherein the plurality of second via holes are arranged on the second substrate such that each column of first via holes is aligned with one corresponding second via hole, and the plurality of third via holes are arranged on the third substrate such that each of the plurality of second via holes are aligned with a corresponding third via hole.